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(54) Title: THERMOSETTING COMPOSITIONS, CURED COMPOSITIONS, AND PREPREGS AND LAMINATES BASED ON SAME

(57) Abstract: This disclosure relates to thermosetting compositions suitable for use in making electronic materials such as circuit board substrates, as well as cured compositions, prepregs and laminates based on such thermosetting compositions. One aspect of the disclosure is a thermosetting composition comprising: a poly(1,4-phenylene ether) component having at least 80% phenylene ether content, the poly(1,4-phenylene ether) component being a poly(1,4-phenylene ether) bis(meth)acrylate component, a bis(vinyl) poly(1,4-phenylene ether) component, or a bis((meth)allyl) poly(1,4-phenylene ether) component, or a combination of two or more thereof; an aromatic crosslinking component having a weight average molecular weight of no greater than 700 g/mol and bearing on numerical average in the range of 1.75 - 3.5 crosslinkable vinyl, (meth)allyl and/or (meth)acrylate groups per molecule; a butadiene/styrene copolymeric rubber component; microparticulate silica; a halogen-free organic fire retardant component; and an effective amount of a thermal free-radical initiator component.

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